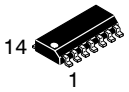
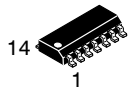
Hex Inverter

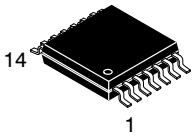
74AC04, 74ACT04



SOIC-14 NB
CASE 751A-03



SOIC14
CASE 751EF



TSSOP-14 WB
CASE 948G

General Description

The AC/ACT04 contains six inverters.

Features

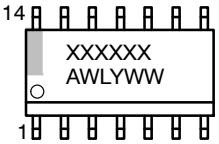
- I_{CC} Reduced by 50% On 74AC Only
- Outputs Source/Sink 24 mA
- ACT04 has TTL-Compatible Inputs
- These are Pb-Free Devices

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Supply Voltage	V_{CC}	−0.5 to +6.5	V
DC Input Diode Current V_I = −0.5 V V_I = V_{CC} + 0.5 V	I_{IK}	 −20 +20	mA
DC Input Voltage	V_I	−0.5 to V_{CC} + 0.5	V
DC Output Diode Current V_O = −0.5 V V_O = V_{CC} + 0.5 V	I_{OK}	 −20 +20	mA
DC Output Voltage	V_O	−0.5 to V_{CC} + 0.5	V
DC Output Source or Sink Current	I_O	±50	mA
DC V_{CC} or Ground Current per Output Pin	I_{CC} or I_{GND}	±50	mA
Storage Temperature Range	T_{STG}	−65 to +150	°C
Junction Temperature	T_J	140	°C

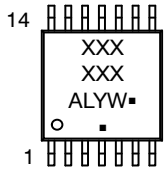
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

MARKING DIAGRAM



XXXXXX	= Specific Device Code
A	= Assembly Location
WL	= Wafer Lot
Y	= Year
WW	= Work Week

MARKING DIAGRAM



XXXXXX	= Specific Device Code
A	= Assembly Location
L	= Wafer Lot
Y	= Year
W	= Work Week
▪	= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

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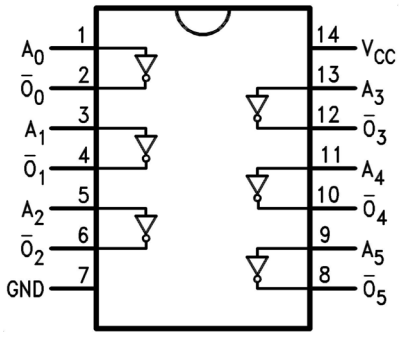


Figure 1. Connection Diagram

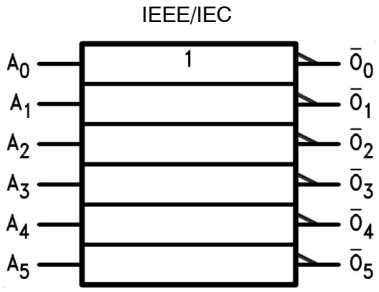


Figure 2. Logic Symbol

PIN DESCRIPTION

Pin	Description
A_n	Inputs
$\overline{O}_n$	Outputs

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	Supply Voltage AC ACT	 2.0 4.5	 6.0 5.5	V
V_I	Input Voltage	0	V_{CC}	V
V_O	Output Voltage	0	V_{CC}	V
T_A	Operating Temperature	−40	+85	°C
$\Delta V / \Delta t$	Minimum Input Edge Rate, AC Devices: V_{IN} from 30% to 70% of V_{CC}, V_{CC} at 3.3 V, 4.5 V, 5.5 V	125		mV/ns
$\Delta V / \Delta t$	Minimum Input Edge Rate, ACT Devices: V_{IN} from 0.8 V to 2.0 V, V_{CC} at 4.5 V, 5.5 V	125		mV/ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

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DC ELECTRICAL CHARACTERISTICS FOR AC

Symbol	Parameter	V_{CC}(V)	Conditions	T_A = +25 °C	T_A = −40 °C to +85 °C		Unit
				Typ	Guaranteed Limits		
V_{IH}	Minimum HIGH Level Input Voltage	3.0	V_{OUT} = 0.1 V or V_{CC} − 0.1 V	1.5	2.1	2.1	V
		4.5		2.25	3.15	3.15	
		5.5		2.75	3.85	3.85	
V_{IL}	Maximum LOW Level Input Voltage	3.0	V_{OUT} = 0.1 V or V_{CC} − 0.1 V	1.5	0.9	0.9	V
		4.5		2.25	1.35	1.35	
		5.5		2.75	1.65	1.65	
V_{OH}	Minimum HIGH Level Output Voltage	3.0	I_{OUT} = −50 μA	2.99	2.9	2.9	V
		4.5		4.49	4.4	4.4	
		5.5		5.49	5.4	5.4	
		3.0	V_{IN} = V_{IL} or V_{IH}, I_{OH} = −12 mA		2.56	2.46	
		4.5	I_{OH} = −24 mA		3.86	3.76	
		5.5	I_{OH} = −24 mA (Note 1)		4.86	4.76	
V_{OL}	Maximum LOW Level Output Voltage	3.0	I_{OUT} = 50 μA	0.002	0.1	0.1	V
		4.5		0.001	0.1	0.1	
		5.5		0.001	0.1	0.1	
		3.0	V_{IN} = V_{IL} or V_{IH}, I_{OL} = 12 mA		0.36	0.44	
		4.5	I_{OL} = 24 mA		0.36	0.44	
		5.5	I_{OL} = 24 mA (Note 1)		0.36	0.44	
I_{IN} (Note 3)	Maximum Input Leakage Current	5.5	V_I = V_{CC}, GND		±0.1	±1.0	μA
I_{OLD}	Minimum Dynamic Output Current (Note 2)	5.5	V_{OLD} = 1.65 V Max.			75	mA
I_{OHD}		5.5	V_{OHD} = 3.85 V Min.			−75	mA
I_{CC} (Note 3)	Maximum Quiescent Supply Current	5.5	V_{IN} = V_{CC} or GND		2.0	20.0	μA

1. All outputs loaded; thresholds on input associated with output under test.
2. Maximum test duration 2.0 ms, one output loaded at a time.
3. I_{IN} and I_{CC} at 3.0 V are guaranteed to be less than or equal to the respective limit at 5.5 V V_{CC}.

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DC ELECTRICAL CHARACTERISTICS FOR ACT

Symbol	Parameter	V_{CC}(V)	Conditions	T_A = +25 °C	T_A = −40 °C to +85 °C		Unit
				Typ	Guaranteed Limits		
V_{IH}	Minimum HIGH Level Input Voltage	4.5	V_{OUT} = 0.1 V or V_{CC} − 0.1 V	1.5	2.0	2.0	V
		5.5		1.5	2.0	2.0	
V_{IL}	Maximum LOW Level Input Voltage	4.5	V_{OUT} = 0.1 V or V_{CC} − 0.1 V	1.5	0.8	0.8	V
		5.5		1.5	0.8	0.8	
V_{OH}	Minimum HIGH Level Output Voltage	4.5	I_{OUT} = −50 μA	4.49	4.4	4.4	V
		5.5		5.49	5.4	5.4	
		4.5	V_{IN} = V_{IL} or V_{IH} I_{OH} = −24 mA		3.86	3.76	
		5.5	I_{OH} = −24 mA (Note 4)		4.86	4.76	
V_{OL}	Maximum LOW Level Output Voltage	4.5	I_{OUT} = 50 μA	0.001	0.1	0.1	V
		5.5		0.001	0.1	0.1	
		4.5	V_{IN} = V_{IL} or V_{IH} I_{OL} = 24 mA		0.36	0.44	
		5.5	I_{OL} = 24 mA (Note 4)		0.36	0.44	
I_{IN}	Maximum Input Leakage Current	5.5	V_I = V_{CC}, GND		±0.1	±1.0	μA
I_{CCT}	Maximum I_{CC}/Input	5.5	V_I = V_{CC} − 2.1 V	0.6		1.5	mA
I_{OLD}	Minimum Dynamic Output Current (Note 5)	5.5	V_{OLD} = 1.65 V Max.			75	mA
I_{OHD}		5.5	V_{OHD} = 3.85 V Min.			−75	mA
I_{CC}	Maximum Quiescent Supply Current	5.5	V_{IN} = V_{CC} or GND		4.0	40.0	μA

4. All outputs loaded; thresholds on input associated with output under test.
5. Maximum test duration 2.0 ms, one output loaded at a time.

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AC ELECTRICAL CHARACTERISTICS FOR AC

Symbol	Parameter	V_{CC}(V) (Note 6)	T_A = +25 °C, C_L = 50 pF			T_A = −40 °C to +85 °C, C_L = 50 pF		Unit
			Min	Typ	Max	Min	Max	
t_{PLH}	Propagation Delay	3.3	1.5	4.5	9.0	1.0	10.0	ns
		5.0	1.5	4.0	7.0	1.0	7.5	
t_{PHL}	Propagation Delay	3.3	1.5	4.5	8.5	1.0	9.5	ns
		5.0	1.5	3.5	6.5	1.0	7.0	

6. Voltage range 3.3 is 3.3 V + 0.3 V. Voltage range 5.0 is 5.0 V + 0.5 V.

AC ELECTRICAL CHARACTERISTICS FOR ACT

Symbol	Parameter	V_{CC}(V) (Note 7)	T_A = +25 °C, C_L = 50 pF			T_A = −40 °C to +85 °C, C_L = 50 pF		Unit
			Min	Typ	Max	Min	Max	
t_{PLH}	Propagation Delay	5.0	1.0	6.0	8.5	1.0	9.0	ns
t_{PLH}	Propagation Delay	5.0	1.0	5.5	8.0	1.0	8.5	ns

7. Voltage range 5.0 is 5.0 V + 0.5 V.

CAPACITANCE

Symbol	Parameter	Conditions	Typ	Unit
C_{IN}	Input Capacitance	V_{CC} = OPEN	4.5	pF
V_{CC}	Power Dissipation Capacitance	V_{CC} = 5.0 V	30.0	pF

ORDERING INFORMATION

Order Number	Marking	Package	Shipping†
74AC04SC	AC04G	SOIC-14 NB, Case 751A-03	55 Units / Rail
74AC04SCX	AC04G	SOIC-14, Case 751EF	2500 / Tape & Reel
74ACT04MTC	ACT 04	TSSOP-14 WB	96 Units / Rail
74AC04MTCX	AC 04	TSSOP-14 WB	2500 / Tape & Reel
74ACT04SC	ACT04G	SOIC-14 NB, Case 751A-03	55 Units / Rail
74ACT04SCX	ACT04G	SOIC-14, Case 751EF	2500 / Tape & Reel
74ACT04MTCX	ACT 04	TSSOP-14 WB	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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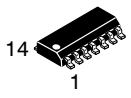
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REVISION HISTORY

Revision	Description of Changes	Date
5	Edits to the package name labels.	10/26/2026

This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.

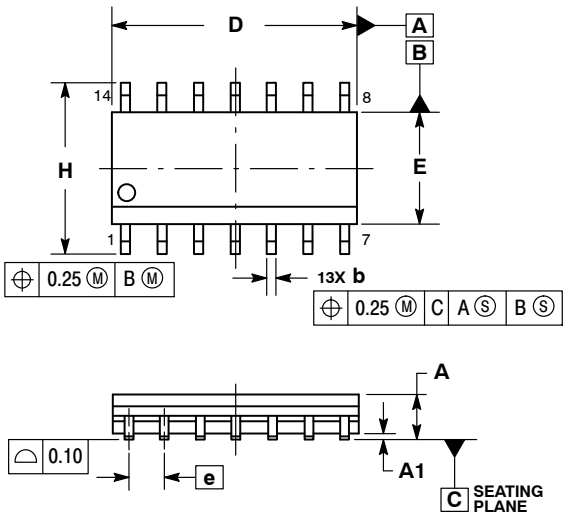
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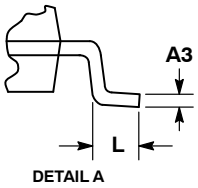


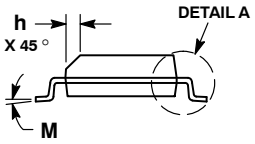
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SOIC−14 NB
CASE 751A−03
ISSUE L

DATE 03 FEB 2016



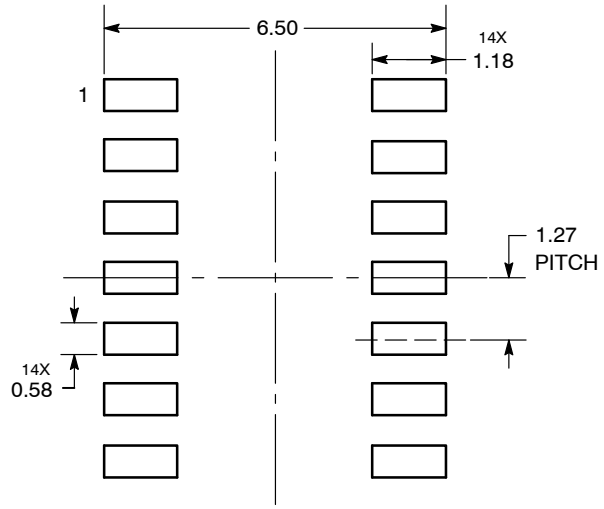




NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0 °	7 °	0 °	7 °

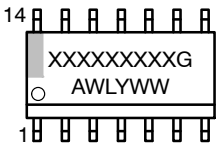
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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SOIC−14
CASE 751A−03
ISSUE L

DATE 03 FEB 2016

STYLE 1:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. NO CONNECTION
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. NO CONNECTION
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 2:
CANCELLED

STYLE 3:
PIN 1. NO CONNECTION
2. ANODE
3. ANODE
4. NO CONNECTION
5. ANODE
6. NO CONNECTION
7. ANODE
8. ANODE
9. ANODE
10. NO CONNECTION
11. ANODE
12. ANODE
13. NO CONNECTION
14. COMMON CATHODE

STYLE 4:
PIN 1. NO CONNECTION
2. CATHODE
3. CATHODE
4. NO CONNECTION
5. CATHODE
6. NO CONNECTION
7. CATHODE
8. CATHODE
9. CATHODE
10. NO CONNECTION
11. CATHODE
12. CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 5:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. NO CONNECTION
7. COMMON ANODE
8. COMMON CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 6:
PIN 1. CATHODE
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. ANODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE

STYLE 7:
PIN 1. ANODE/CATHODE
2. COMMON ANODE
3. COMMON CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. ANODE/CATHODE
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
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12. COMMON ANODE
13. ANODE/CATHODE
14. ANODE/CATHODE

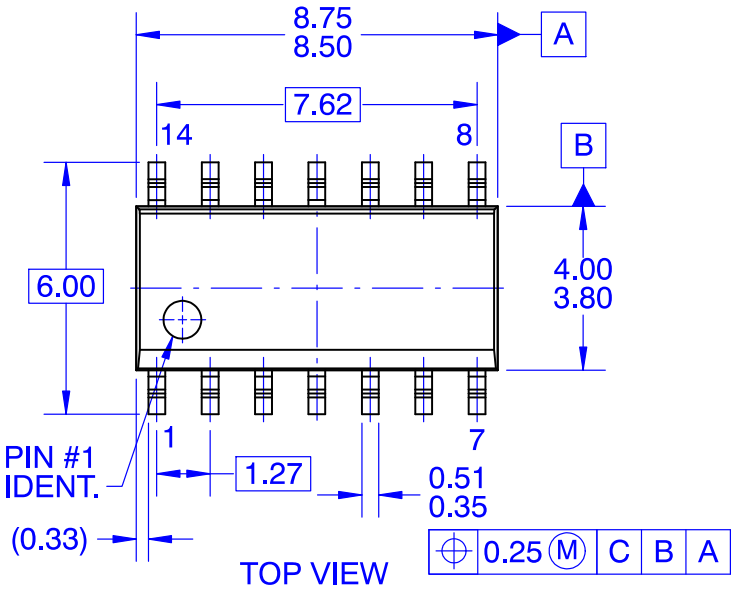
STYLE 8:
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2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. ANODE/CATHODE
7. COMMON ANODE
8. COMMON ANODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. NO CONNECTION
12. ANODE/CATHODE
13. ANODE/CATHODE
14. COMMON CATHODE

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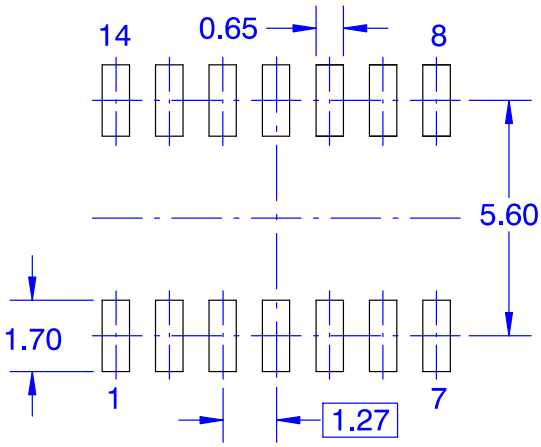
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SOIC14
CASE 751EF
ISSUE O

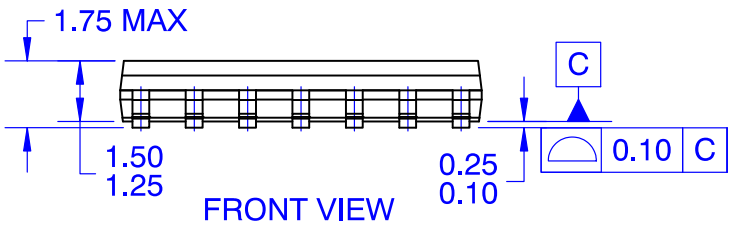
DATE 30 SEP 2016



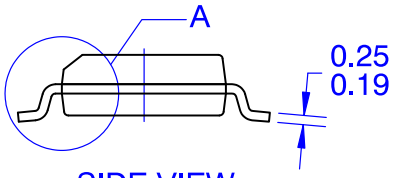
TOP VIEW



LAND PATTERN RECOMMENDATION

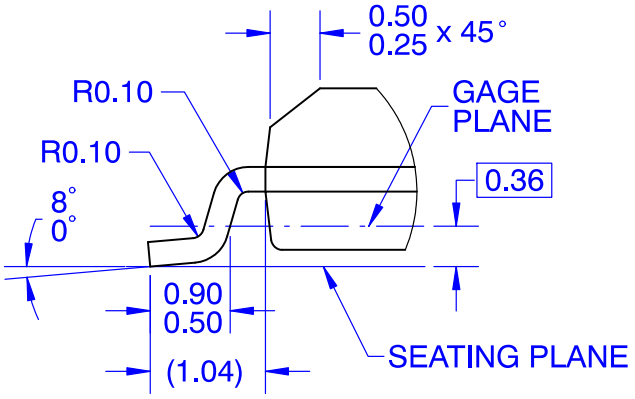


FRONT VIEW



SIDE VIEW

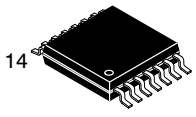
NOTES:
A. CONFORMS TO JEDEC MS−012, VARIATION AB, ISSUE C
B. ALL DIMENSIONS ARE IN MILLIMETERS
C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS
D. LAND PATTERN STANDARD: SOIC127P600X145−14M
E. CONFORMS TO ASME Y14.5M, 2009



DETAIL A
SCALE 16 : 1

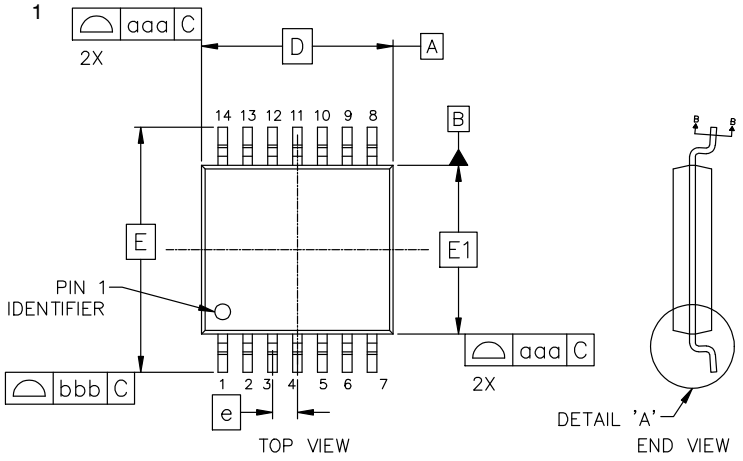
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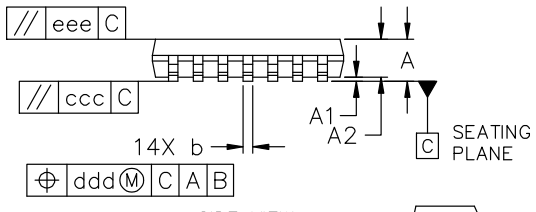
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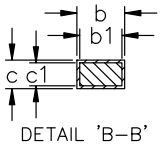


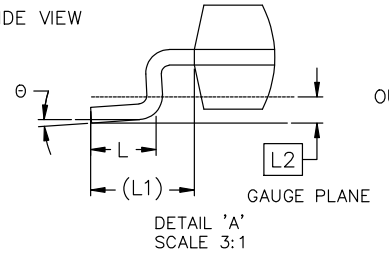
TSSOP−14 5.00x4.40x0.95, 0.65P
CASE 948G
ISSUE D

DATE 30 JUN 2026

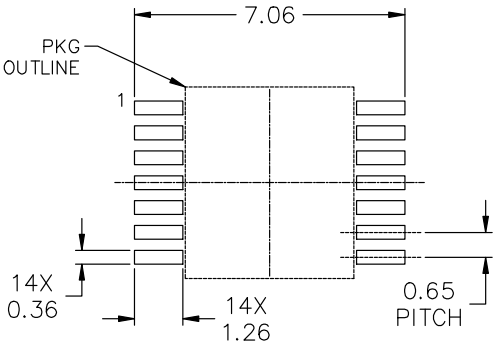








MILLIMETERS			
DIM	MIN	NOM	MAX
A	−−−	−−−	1.20
A1	0.05	0.10	0.15
A2	0.85	0.95	1.05
b	0.19	0.25	0.30
b1	0.19	0.22	0.25
c	0.09	0.15	0.20
c1	0.09	0.12	0.16
D	5.00 BSC		
E	6.40 BSC		
E1	4.40 BSC		
e	0.65 BSC		
L	0.50	0.63	0.75
L1	1.00 REF		
L2	0.25 BSC		
θ	0°	4°	8°
TOLERANCE FORM & POSITION			
aaa	0.10		
bbb	0.15		
ccc	0.08		
ddd	0.10		
eee	0.10		

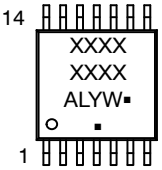


RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb−Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:
1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION D DOES NOT INCLIDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.
4. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

GENERIC MARKING DIAGRAM*



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package
(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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